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BSI Standards Publication

Test methods for electrical materials, printed boards and other interconnection structures and assemblies

Part 3-301: Test methods for interconnection structures (printed boards) — Appearance inspection method for plated surfaces on PWB

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National foreword

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A list of organizations represented on this committee can be obtained on request to its secretary.

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colour inside

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 3-301: Test methods for interconnection structures (printed boards) – Appearance inspection method for plated surfaces on PWB

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IEC TS 61189-3-301, which is a technical specification, has been prepared by IEC technical committee 91: Electronics assembly technology.

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The text of this technical specification is based on the following documents:

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91/1348/DTS	91/1376/RVC

Full information on the voting for the approval of this technical specification can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- transformed into an International standard,
- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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